



1 *Silicate Bonding applied to various glass blanks (diameter 25 mm, SiO₂, BK7, glass-ceramics).*

2 *Direct Bonding of a glass wafer to a thick glass substrate (diameter 200 mm, SiO₂, preliminary).*

3 *Direct Bonding of glass blanks (diameter 25 mm, SiO₂, coated and uncoated).*

Fraunhofer Institute for Applied Optics and Precision Engineering IOF

Albert-Einstein-Straße 7
07745 Jena

Director
Prof. Dr. Andreas Tünnermann

Head of Business Unit Precision Engineering Components and Systems
Dr. Ramona Eberhardt

Contact
Dr.-Ing. Stefan Risse
Phone +49 3641 807-313
stefan.risse@iof.fraunhofer.de

www.iof.fraunhofer.de

BONDING TECHNOLOGIES ADAPTED TO GLASS AND GLASS-CERAMICS

Objective

Development of "adapted" bonding technologies for glass and glass-ceramics using water based silicate solutions or no additives at all ("Direct Bonding") by applying suitable surface activation processes before assembly in a vacuum environment.

Pre-conditions

- Materials with a high SiO₂ content
- Surfaces highly plane (or otherwise conform), flatness at least $\lambda/10$ PV*
- Extremely smooth (polished) surfaces, roughness < 1 nm RMS*

* λ : wavelength (632 nm)
PV: peak-to-valley
RMS: root-mean-square

Bond characteristics

- Full transparency (bonding area is "invisible")
- No uncontrolled creep/drift under mechanical load
- No outgassing at elevated temperatures
- No stress from thermal mismatch (for identical materials)
- Assembly of individual parts "accurate to gage blocks"

Applications

- UV, VIS and IR optics (transmission and reflection)
- Laser applications
- Space applications
- Lithography and precision engineering applications